

SS12FP – S115FP

THERMAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted) (Note 1)

| Symbol | Parameter | Value | Unit |
|-----------------|--|-------|---------------------------|
| Ψ_{JL} | Thermal Characteristics, Junction-to-Lead (Note 2) | 10 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 140 | $^\circ\text{C}/\text{W}$ |

- Per JESD51-3 recommended thermal test board. Device mounted on FR-4 PCB, board size = 76.2 mm x 114.3 mm.
- Thermocouple soldered at cathode lead.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Value | | | | | | Unit |
|----------|--|---|---------|---------|---------|---------|---------|---------|------|
| | | | SS12 FP | SS13 FP | SS14 FP | SS16 FP | S110 FP | S115 FP | |
| V_F | Maximum Instantaneous Forward Voltage (Note 3) | $I_F = 0.5 \text{ A}$ | | | 0.51 | 0.58 | 0.70 | 0.75 | V |
| | | $I_F = 1.0 \text{ A}$ | 0.45 | 0.50 | 0.55 | 0.70 | 0.80 | 0.90 | |
| I_R | Maximum Reverse Current at Rated V_R | $T_J = 25^\circ\text{C}$ | 0.40 | | | | 0.05 | | mA |
| | | $T_J = 125^\circ\text{C}$ | | | | | 0.50 | | |
| C_J | Typical Junction Capacitance | $V_R = 4 \text{ V}$, $f = 1 \text{ MHz}$ | 54 | | | | 28 | | pF |
| T_{rr} | Typical Reverse Recovery Time | $I_F = 0.5 \text{ A}$, $I_R = 1 \text{ A}$, $I_{RR} = 0.25 \text{ A}$ | 6 | | | | 14 | | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Pulse test with $PW = 300 \mu\text{s}$, 1% duty cycle.

ORDERING INFORMATION

| Part Number | Device Code Marking | Package | Packing Method [†] |
|-------------|---------------------|-----------|-----------------------------|
| SS12FP | 2FP | SOD-123EP | Tape and Reel |
| SS13FP | 3FP | SOD-123EP | Tape and Reel |
| SS14FP | 4FP | SOD-123EP | Tape and Reel |
| SS16FP | 6FP | SOD-123EP | Tape and Reel |
| S110FP | 0FP | SOD-123EP | Tape and Reel |
| S115FP | AFP | SOD-123EP | Tape and Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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TYPICAL PERFORMANCE CHARACTERISTICS

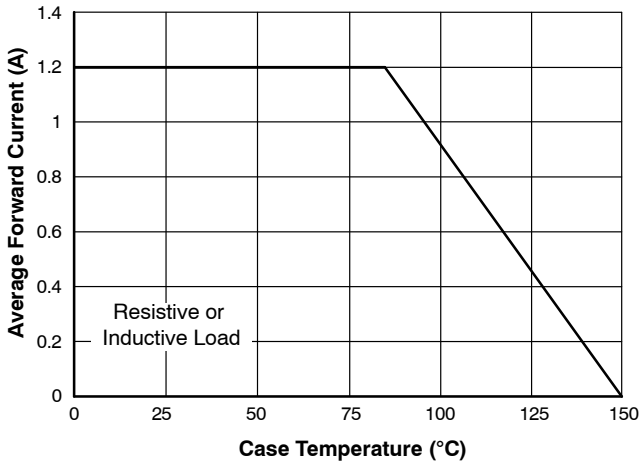


Figure 1. Forward Current Derating Curve

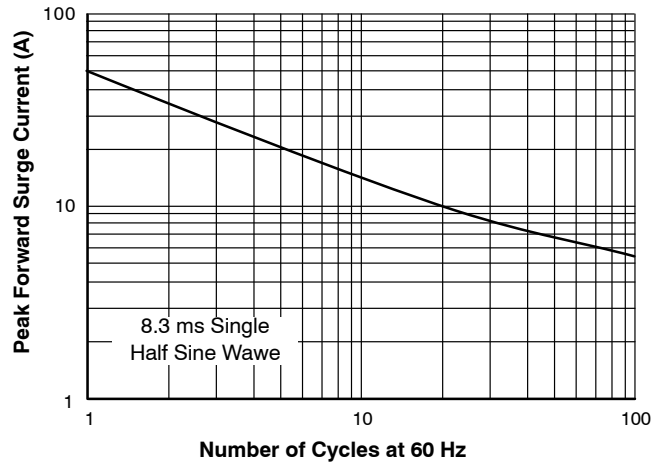


Figure 2. Maximum Non-Repetitive Forward Surge Current

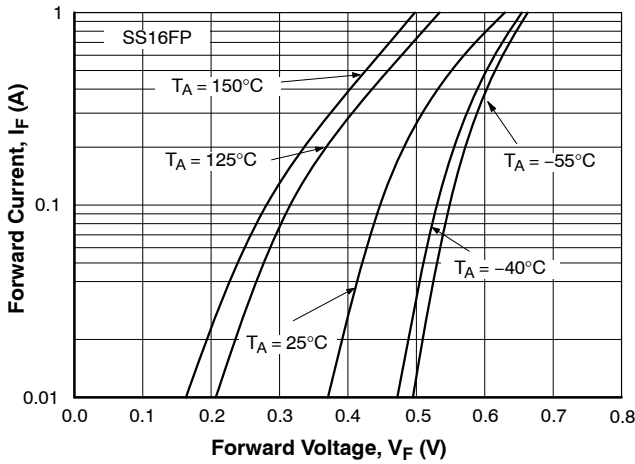


Figure 3. Typical Forward Characteristics

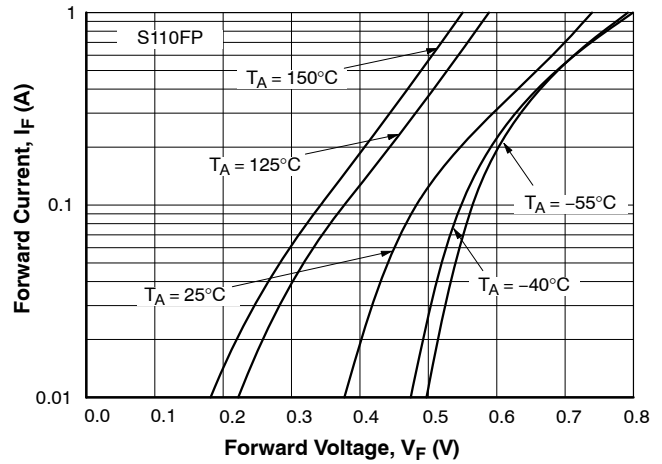


Figure 4. Typical Forward Characteristics

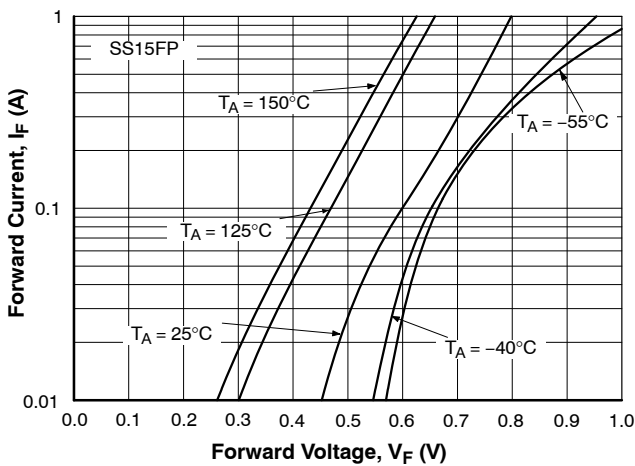


Figure 5. Typical Forward Characteristic

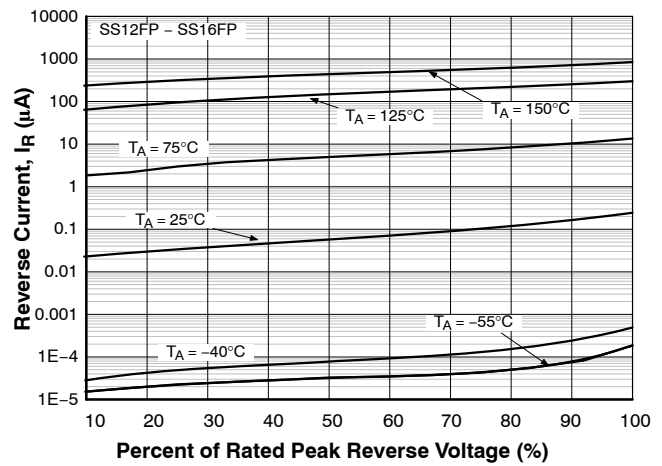


Figure 6. Typical Reverse Characteristics

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TYPICAL PERFORMANCE CHARACTERISTICS

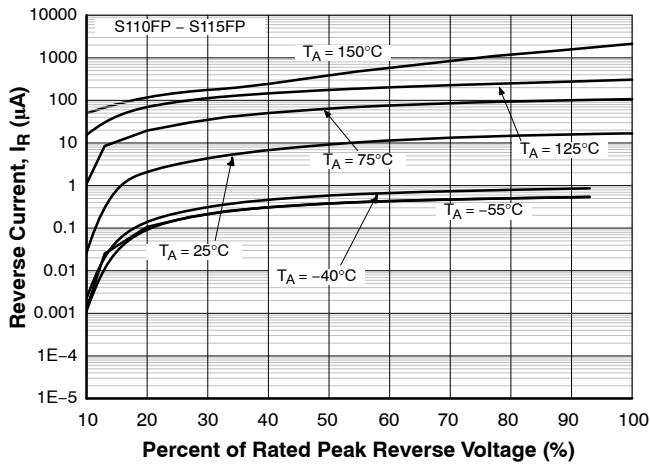


Figure 7. Typical Reverse Characteristic

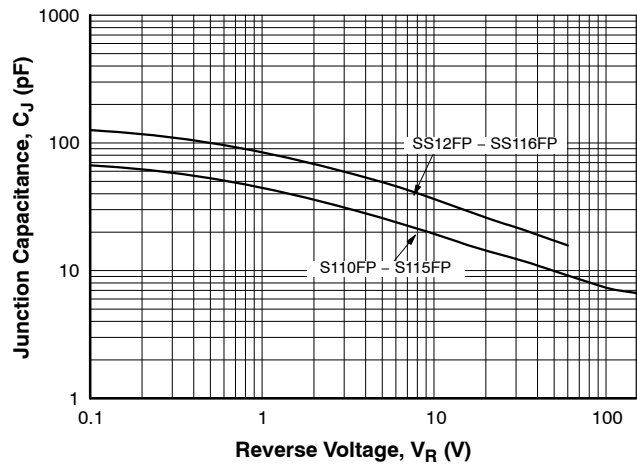


Figure 8. Typical Junction Capacitance

MECHANICAL CASE OUTLINE

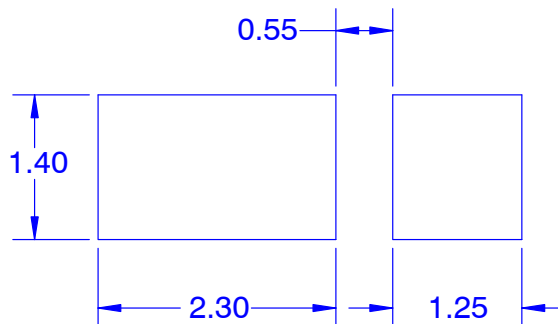
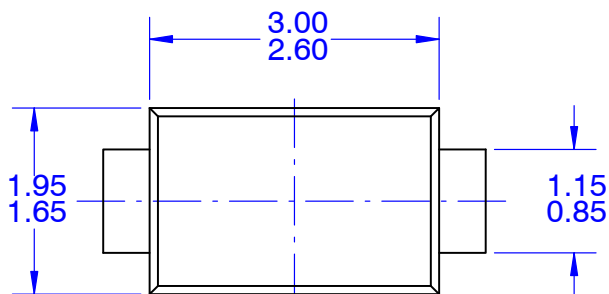
PACKAGE DIMENSIONS

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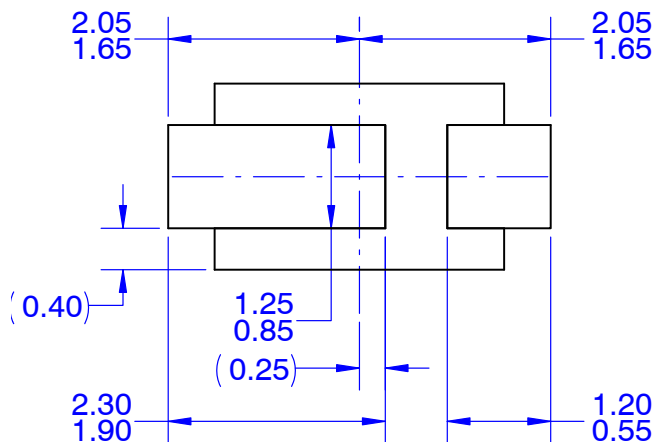
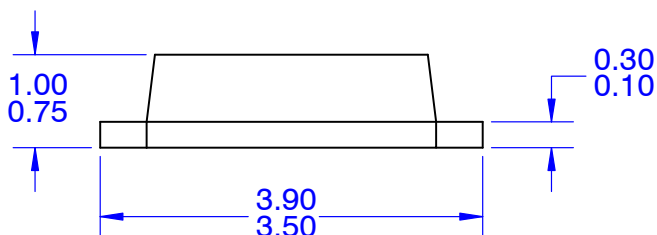


SOD-123EP
CASE 425AC
ISSUE O

DATE 31 AUG 2016



LAND PATTERN RECOMMENDATION
LONG PAD IS CATHODE



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- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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